## SERIAL NO. ATTY DOCKET NO. END920010002 INFORMATION DISCLOSURE CITATION Sudipta K. Ray et al. (Use several sheets if necessary) FILING GROUP **U.S. PATENT DOCUMENTS** \*EXAMINER FILING DATE CLASS SUBCLASS NAME DOCUMENT NUMBER DATE IF APPROPRIATE INITIAL 6,077,477 6/2000 Sakai et al. )*}*~ 420 530 6/1996 Anderson et al. 5,527,628 428 647 5,221,038 6/1993 Melton et al. 228 180 9/1992 Behun et al. 5,147,084 228 56.3 4,875,617 10/1989 Citowsky 228 123 10/1988 Lubrano et al. 4,778,733 428 647 Anderson 2/1973 3,716,907 29 470.9 2,105,405 1/1936 Chase

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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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